INTEGRATED CIRCUITS

DATA SHEET

TSA5515T 1.3 GHz bi-directional I²C-bus controlled synthesizer

Product specification
File under Integrated Circuits, IC02

November 1991







1.3 GHz bi-directional I²C-bus controlled synthesizer

TSA5515T

GENERAL DESCRIPTION

The TSA5515T is a single chip PLL frequency synthesizer designed for TV tuning systems. Control data is entered via the l²C-bus; five serial bytes are required to address the device, select the oscillator frequency, programme the three output ports and set the charge-pump current. A flag is set when the loop is "in-lock". Another flag is set when a power dip occurs on the supply line. These flags are read out of the TSA5515T on SDA line (one status byte) during a READ operation. The device has 4 programmable addresses, programmed by applying a specific voltage on the AS pin. The phase comparator operates at 7.8125 kHz when a 4 MHz crystal is used.



- In-lock flag
- · Varicap drive disable
- Low radiation
- Address selection for Picture-In-Picture (PIP), DBS tuner, etc.
- 3 bus-controlled output ports
- Power-down flag
- Available in SOT108A package

FEATURES

- Complete 1.3 GHz single-chip system
- Low power 5 V, 35 mA
- I²C-bus programming

APPLICATIONS

- TV tuners
- VCR tuners

QUICK REFERENCE DATA

| SYMBOL | PARAMETER | MIN. | TYP. | MAX. | UNIT |
|----------------------|-------------------------------------|------|------|------|------|
| V _{CC} | supply voltage | _ | 5 | _ | V |
| Icc | supply current | _ | 35 | _ | mA |
| Δf | frequency range | 64 | _ | 1300 | MHz |
| V _{I (RMS)} | input voltage level (RMS value) | | | | |
| | 80 MHz to 150 MHz | 12 | _ | 300 | mV |
| | 150 MHz to 1 GHz | 9 | _ | 300 | mV |
| | 1 GHz to 1.3 GHz | 40 | _ | 300 | mV |
| f _{XTAL} | crystal oscillator | 3.2 | 4 | 4.48 | MHz |
| Io | open-collector output current | | | | |
| | P7 | _ | _ | 5 | mA |
| | P1, P2 | _ | _ | 20 | mA |
| T _{amb} | operating ambient temperature range | -10 | _ | 80 | °C |
| T _{stg} | storage temperature range | -40 | _ | 125 | °C |
| R _{th j-a} | thermal resistance | _ | 110 | _ | K/W |

ORDERING INFORMATION

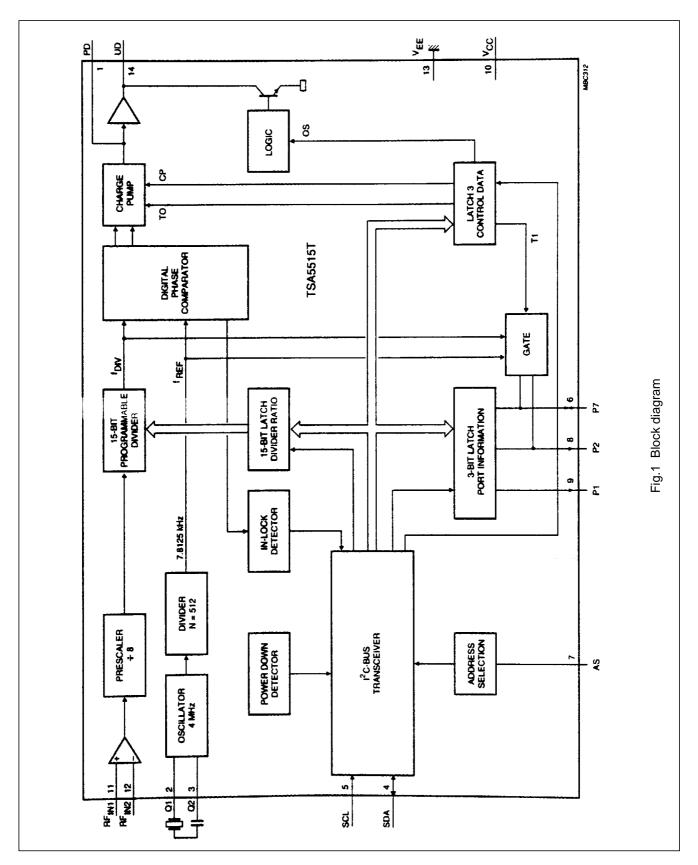
| EXTENDED TYPE NUMBER | PACKAGE | | | | | | | | | |
|-----------------------|---------|--------------|----------|------------------------|--|--|--|--|--|--|
| LATENDED TIFE NOWIDER | PINS | PIN POSITION | MATERIAL | CODE | | | | | | |
| TSA5515T | 14 | so | plastic | SOT108A ⁽¹⁾ | | | | | | |

Note

1. SOT108-1; 1996 December 3.

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LIMITING VALUES

In accordance with Absolute Maximum System (IEC 134).

| SYMBOL | PARAMETER | MIN. | MAX. | UNIT |
|------------------|-------------------------------------|-----------|-----------------|------|
| V _{CC} | supply voltage | -0.3 | 6 | V |
| V _{P1} | charge-pump output voltage | -0.3 | V _{CC} | V |
| V _{P2} | crystal (Q1) input voltage | -0.3 | V _{CC} | V |
| V _{P4} | serial data input/output | -0.3 | 6 | V |
| V _{P5} | serial clock input | -0.3 | 6 | V |
| V _{P7} | address selection | -0.3 | 6 | V |
| V _{P6} | output ports P7, P2, P1 | -0.3 | 16 | V |
| V _{P11} | prescaler inputs | -0.3 | 2.5 | V |
| V _{P14} | drive output | -0.3 | V _{CC} | V |
| I _{6L} | output port P7 (open collector) | -1 | 10 | mA |
| I _{8L} | output port P2, P1 (open collector) | -1 | 25 | mA |
| I _{4L} | SDA output (open collector) | -1 | 5 | mA |
| T _{stg} | storage temperature range | -40 | 125 | °C |
| T _i | junction temperature | _ | 125 | °C |

THERMAL RESISTANCE

| SYMBOL | PARAMETER | THERMAL RESISTANCE |
|---------------------|--------------------------------------|--------------------|
| R _{th j-a} | from junction to ambient in free air | 110 K/W |

HANDLING

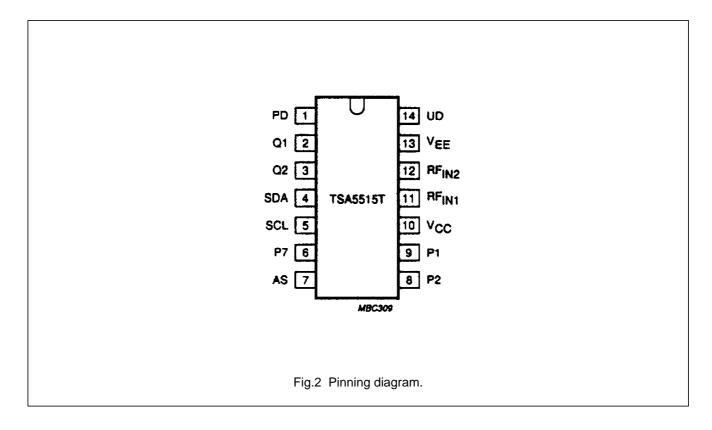
Every pin withstands the ESD test in accordance with MIL-STD-883C, category A (> 1500 V).

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PINNING

| SYMBOL | PIN | DESCRIPTION |
|-------------------|-----|------------------------------------|
| PD | 1 | charge-pump output |
| Q1 | 2 | crystal oscillator input 1 |
| Q2 | 3 | crystal oscillator input 2 |
| SDA | 4 | serial data input/output |
| SCL | 5 | serial clock input |
| P7 | 6 | port output |
| AS | 7 | input for address selection |
| P2 | 8 | port output |
| P1 | 9 | port output |
| V _{CC} | 10 | voltage supply |
| RF _{IN1} | 11 | UHF/VHF signal input 1 |
| RF _{IN2} | 12 | UHF/VHF signal input 2 (decoupled) |
| GND | 13 | ground |
| UD | 14 | drive output |



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FUNCTIONAL DESCRIPTION

The TSA5515T is controlled via the two-wire I^2C -bus. For programming, there is one module address (7 bits) and the R/W bit for selecting READ or WRITE mode.

WRITE mode:

 $R/\overline{W} = 0$ (see Table 1)

After the address transmission (first byte), data bytes can be sent to the device. Four data bytes are needed to fully program the TSA5515T. The bus transceiver has an auto-increment facility, which permits the programming of the TSA5515T within one single transmission (address + 4 data bytes).

The TSA5515T can also be partly programmed on the condition that the first data byte following the address is

byte 2 or byte 4. The meaning of the bits in the data bytes is given in Table 1. The first bit of the first data byte transmitted indicates whether frequency data (first bit = 0) or charge pump and port information (first bit = 1) will follow. Until an I^2C -bus STOP condition is sent by the controller, additional data bytes can be entered without the need to re-address the device. This allows a smooth frequency sweep for fine tuning. At power-on, the ports are set to the high impedance state.

The 7.8125 kHz reference frequency is obtained by dividing the output of the 4 MHz crystal oscillator by 512. Because the input of the UHF/VHF signal is first divided by 8, the step size is 62.5 kHz. A 3.2 MHz crystal can offer a step size of 50 kHz.

Table 1 Write data format

| | MSB | | | | | | LSB | | | |
|---------------------------|-----|-----|-----|-----|-----|-----|-----|----|---|--------|
| Address | 1 | 1 | 0 | 0 | 0 | MA1 | MA0 | 0 | Α | byte 1 |
| Programmable divider | 0 | N14 | N13 | N12 | N11 | N10 | N9 | N8 | А | byte 2 |
| Programmable divider | N7 | N6 | N5 | N4 | N3 | N2 | N1 | N0 | А | byte 3 |
| Charge-pump and test bits | 1 | СР | T1 | T0 | Х | Х | Х | os | А | byte 4 |
| Output ports control bits | P7 | Х | Х | Х | Х | P2 | P1 | Х | Α | byte 5 |

MA1, MA0 programmable address bits (see Table 3)

A acknowledge bit

N14 to N0 programmable divider bits

 $N = N14 \times 2^{14} + N13 \times 2^{13} + ... + N1 \times 2^{1} + N0$

CP charge-pump current

 $\begin{aligned} \text{CP} &= 0 & \text{50 } \mu\text{A} \\ \text{CP} &= 1 & \text{220 } \mu\text{A} \end{aligned}$

P7, P2, P1 = 1 open-collector outputs are active P7, P2, P1 = 0 outputs are in high impedance state

T1, T0, OS = 0.00 normal operation

T1 = 1, $P2 = f_{ref}$, $P7 = f_{DIV}$

T0 = 1 3-state charge-pump

OS = 1 operational amplifier output is switched off (varicap drive disable)

Note

1. X = don't care

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READ mode:

$R/\overline{W} = 1$ (see Table 2)

Data can be read out of the TSA5515T by setting the R/W bit to 1. After the slave address has been recognized, the TSA5515T generates an acknowledge pulse and the first data byte (status word) is transferred on the SDA line (MSB first). Data is valid on the SDA line during a high position of the SCL clock signal.

A second data byte can be read out of the TSA5515T if the processor generates an acknowledge on the SDA line. End of transmission will occur if no acknowledge from the

processor occurs. The TSA5515T will then release the data line to allow the processor to generate a STOP condition.

The POR flag (power-on-reset) is set to 1 when V_{CC} goes below 3 V and at power-on. It is reset when an end of data is detected by the TSA5515T (end of a READ sequence). Control of the loop is made possible with the in-lock flag FL, which indicates (FL = 1) when the loop is phase-locked.

Table 2 Read data format

| | MSB | | | | | | | LSB | | |
|-------------|-----|----|---|---|---|-----|-----|-----|---|--------|
| Address | 1 | 1 | 0 | 0 | 0 | MA1 | MA0 | 1 | Α | byte 1 |
| Status byte | POR | FL | 1 | 1 | 1 | 1 | 1 | 1 | _ | byte 2 |

Notes

- 1. POR power-on-reset flag. (POR = 1 on power-on)
- 2. FL in-lock flag (FL = 1 when the loop is phase-locked).

MSB is transmitted first.

Address selection (see Table 3)

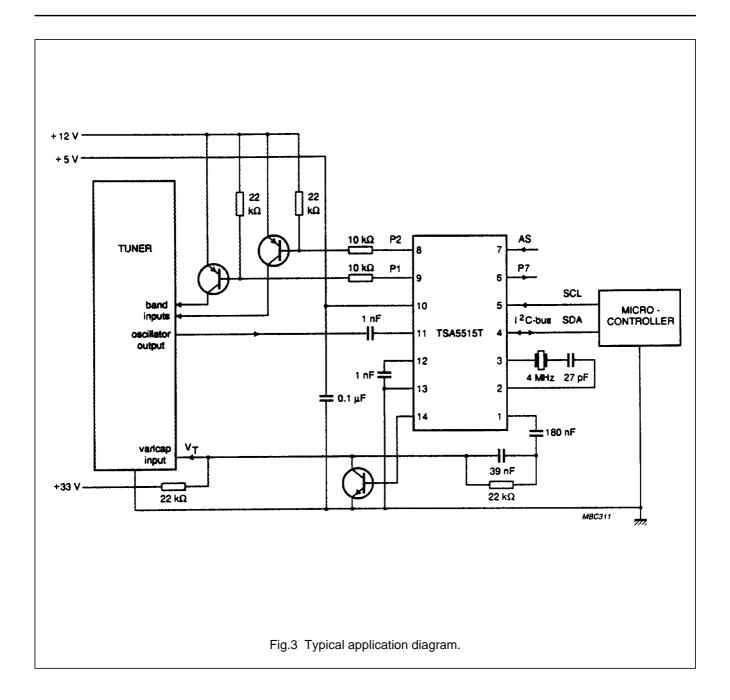
The module address contains programmable address bits (MA1 and MA0), which offer the possibility of having several synthesizers (up to 4) in one system. The relationship between MA1 and MA0 and the input voltage on AS input is given in Table 3.

Table 3 Address selection

| MA1 | MA0 | Voltage applied on AS pin |
|-----|-----|--|
| 0 | 0 | 0 to 0.1 V _{CC} |
| 0 | 1 | open |
| 1 | 0 | 0.4 to 0.6 V _{CC} |
| 1 | 1 | 0.9 V _{CC} to V _{CC} |

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CHARACTERISTICS

 V_{CC} = 5 V; T_{amb} = 25 °C; unless otherwise specified

| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|----------------------|-------------------------------------|---|------|----------|--|------|
| V _{CC} | supply voltage range | | 4.5 | - | 5.5 | V |
| T _{amb} | operating ambient temperature range | | -10 | _ | 80 | °C |
| f _{CLK} | clock input frequency range | | 64 | _ | 1300 | MHz |
| N | divider | | 256 | - | 32767 | |
| I _{CC} | supply current | | 25 | 35 | 50 | mA |
| f _{XTAL} | crystal oscillator frequency | | 3.2 | 4 | 4.48 | MHz |
| Z _I | input impedance (pin 2) | | -480 | -400 | -320 | Ω |
| V _{I (RMS)} | input voltage level (RMS value) | $V_{CC} = 4.5 \text{ to } 5.5 \text{ V};$ | | | | |
| | f = 80 to 150 MHz | $T_{amb} = -10 \text{ to } 80 ^{\circ}\text{C}$ | 12 | _ | 300/2.6 | mV |
| | f = 150 to 1000 MHz | see typical sensitivity | 9 | _ | 300/2.6 | mV |
| | f = 1000 to 1300 MHz | curve in Fig.4 | 40 | _ | 300/2.6 | mV |
| R _I | prescaler input impedance | see Smith chart in Fig.5 | _ | 50 | _ | Ω |
| Cı | input capacitance | | _ | 2 | _ | pF |
| Output po | rts (open collector) (see note 1) | • | | ! | ' | |
| I _{LO} | leakage current | V _{6H} = 13.5 V | _ | _ | 10 | μΑ |
| V _{OL} | output voltage LOW (P7) | I _{6L} = 5 mA note 2 | _ | - | 0.5 | V |
| | output voltage LOW (P2, P1) | I _{8L} = 20 mA note 2 | _ | - | 0.5 | V |
| Address s | election input (AS) | | • | • | • | |
| I _{IH} | input current HIGH | V _{7H} = 5 V | _ | - | 20 | μΑ |
| I _{IL} | input current LOW | V _{7L} = 0 | -20 | - | _ | μΑ |
| Bus inputs | S SCL, SDA | | • | | • | |
| V _{IH} | input voltage HIGH | | 3 | _ | 5.5 | V |
| V _{IL} | input voltage LOW | | _ | _ | 1.5 | V |
| I _{IH} | input current HIGH | $V_{5H} = 5 \text{ V};$ $V_{CC} = 0$ | - | - | 1300 32767 50 4.48 -320 300/2.6 300/2.6 300/2.6 - - 10 0.5 0.5 20 - 15.5 1.5 10 10 | μΑ |
| | | $V_{5H} = 5 \text{ V};$ $V_{CC} = 5 \text{ V}$ | - | - | 10 | μΑ |
| I _{IL} | input current LOW | $V_{5L} = 0;$ $V_{CC} = 0$ | -10 | - | _ | μА |
| | | V _{5L} = 0; V _{CC} = 5 V | -10 | - | - | μΑ |
| Output SD | A (open collector) | | - | - | | 1 |
| I _{LO} | leakage current | V _{4H} = 5.5 V | _ | _ | 10 | μΑ |
| V _{4L} | output voltage | I _{4L} = 3 mA | _ | _ | 0.4 | V |
| V ₁₄ | output voltage | $V_{1L} = 0$ | _ | - | 100 | mV |

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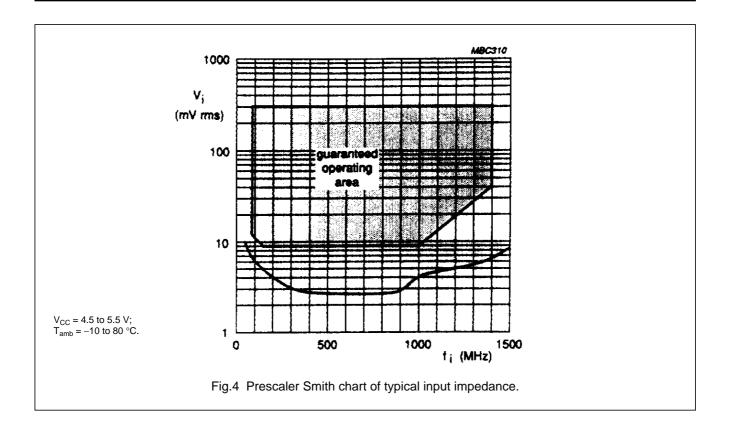
| SYMBOL | PARAMETER | CONDITIONS | MIN. | TYP. | MAX. | UNIT |
|--------------------|--|--|------|------|------|------|
| Charge-pu | mp output PD | | | | | |
| I _{IH} | input current HIGH (absolute value) | CP = 1 | 90 | 220 | 300 | μΑ |
| I _{IL} | input current LOW (absolute value) | CP = 0 | 22 | 50 | 75 | μΑ |
| Vo | output voltage | in-lock | 1.5 | _ | 2.5 | V |
| I _{1leak} | off-state leakage current | T0 = 1 | -5 | _ | 5 | nA |
| Operationa | al amplifier output UD (test mode: T | 0 = 1) | | | • | |
| V ₁₄ | output voltage | $V_{1L} = 0$ | _ | _ | 100 | mV |
| | output voltage when switched off | T0 = 1; OS = 1; V _{1L} = 2 V | - | _ | 200 | mV |
| h _{FE} | operational amplifier current gain I ₁₄ /(I ₁ - I _{1leak}) | T0 = 1; OS = 0; $V_{1L} = 2 V;$ $I_{14} = 10 \mu A$ | 2000 | _ | _ | |

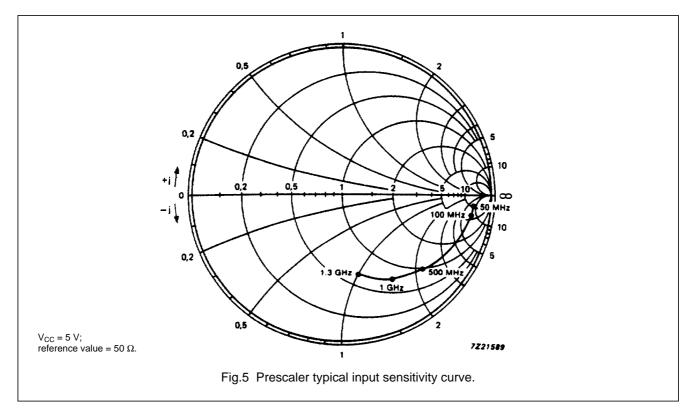
Notes to the characteristics

- 1. When a port is active, the collector voltage must not exceed 6 V.
- 2. A maximum of 1 port at the same time may sink 5 or 20 mA, to guarantee V_{O} = 0.5 V.

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FLOCK FLAG DEFINITION (FL)

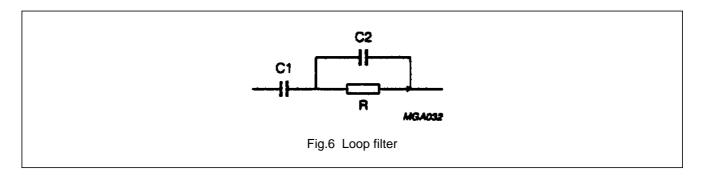
When the FL flag is 1, the maximum frequency deviation (Δf) from stable frequency can be expressed as follows: $\Delta f = \pm (K_{VCO}/K_O) \times I_{CP} \times (C1 + C2) / (C1 \times C2)$

where;

 K_{VCO} = oscillator slope (Hz/V) I_{CP} = charge-pump current (A)

 $K_O = 4 \times 10^6$

C1 and C2 = loop filter capacitors



FLOCK FLAG APPLICATION

- K_{VCO} = 16 MHz/V (UHF band)
- $I_{CP} = 220 \, \mu A$
- C1 = 180 nF
- C2 = 39 nF
- $\Delta f = \pm 27.5 \text{ kHz}.$

Table 4 Flock flag settings

| | MIN. | MAX. | UNIT |
|--|------|------|------|
| Time span between actual phase lock and FL-flag setting | 1024 | 1152 | μs |
| Time span between the loop losing lock and FL-flag resetting | 0 | 128 | μs |

12

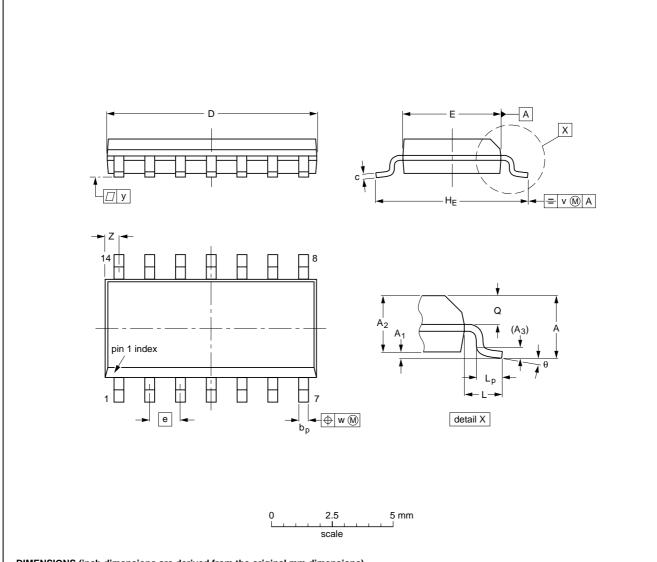
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PACKAGE OUTLINE

SO14: plastic small outline package; 14 leads; body width 3.9 mm

SOT108-1



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

| | imization (in or dimensional district from the original film dimensions) | | | | | | | | | | | | | | | | | |
|--------|--|----------------|----------------|----------------|--------------|------------------|------------------|------------------|-------|----------------|-------|----------------|------------|------|------|-------|------------------|----|
| UNIT | A max. | A ₁ | A ₂ | A ₃ | bp | С | D ⁽¹⁾ | E ⁽¹⁾ | е | HE | L | Lp | Q | v | w | у | z ⁽¹⁾ | θ |
| mm | 1.75 | 0.25 0.10 | 1.45 1.25 | 0.25 | 0.49 0.36 | 0.25 0.19 | 8.75 8.55 | 4.0 3.8 | 1.27 | 6.2 5.8 | 1.05 | 1.0 0.4 | 0.7 0.6 | 0.25 | 0.25 | 0.1 | 0.7 0.3 | 8° |
| inches | 0.069 | 0.010 0.004 | 0.057 0.049 | 0.01 | | 0.0100 0.0075 | 0.35 0.34 | 0.16 0.15 | 0.050 | 0.244 0.228 | 0.041 | 0.039 0.016 | | 0.01 | 0.01 | 0.004 | 0.028 0.012 | 0° |

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

| OUTLINE VERSION | REFERENCES | | | | EUROPEAN | ISSUE DATE |
|--------------------|------------|----------|------|--|------------|---------------------------------|
| | IEC | JEDEC | EIAJ | | PROJECTION | ISSUE DATE |
| SOT108-1 | 076E06S | MS-012AB | | | | 95-01-23 97-05-22 |

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SOLDERING

Introduction

There is no soldering method that is ideal for all IC packages. Wave soldering is often preferred when through-hole and surface mounted components are mixed on one printed-circuit board. However, wave soldering is not always suitable for surface mounted ICs, or for printed-circuits with high population densities. In these situations reflow soldering is often used.

This text gives a very brief insight to a complex technology. A more in-depth account of soldering ICs can be found in our "IC Package Databook" (order code 9398 652 90011).

Reflow soldering

Reflow soldering techniques are suitable for all SO packages.

Reflow soldering requires solder paste (a suspension of fine solder particles, flux and binding agent) to be applied to the printed-circuit board by screen printing, stencilling or pressure-syringe dispensing before package placement.

Several techniques exist for reflowing; for example, thermal conduction by heated belt. Dwell times vary between 50 and 300 seconds depending on heating method. Typical reflow temperatures range from 215 to 250 °C.

Preheating is necessary to dry the paste and evaporate the binding agent. Preheating duration: 45 minutes at $45 \, ^{\circ}\text{C}$.

Wave soldering

Wave soldering techniques can be used for all SO packages if the following conditions are observed:

- A double-wave (a turbulent wave with high upward pressure followed by a smooth laminar wave) soldering technique should be used.
- The longitudinal axis of the package footprint must be parallel to the solder flow.
- The package footprint must incorporate solder thieves at the downstream end.

During placement and before soldering, the package must be fixed with a droplet of adhesive. The adhesive can be applied by screen printing, pin transfer or syringe dispensing. The package can be soldered after the adhesive is cured.

Maximum permissible solder temperature is 260 °C, and maximum duration of package immersion in solder is 10 seconds, if cooled to less than 150 °C within 6 seconds. Typical dwell time is 4 seconds at 250 °C.

A mildly-activated flux will eliminate the need for removal of corrosive residues in most applications.

Repairing soldered joints

Fix the component by first soldering two diagonally-opposite end leads. Use only a low voltage soldering iron (less than 24 V) applied to the flat part of the lead. Contact time must be limited to 10 seconds at up to 300 °C. When using a dedicated tool, all other leads can be soldered in one operation within 2 to 5 seconds between 270 and 320 °C.

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DEFINITIONS

| Data sheet status | | | | |
|---------------------------|---|--|--|--|
| Objective specification | This data sheet contains target or goal specifications for product development. | | | |
| Preliminary specification | This data sheet contains preliminary data; supplementary data may be published later. | | | |
| Product specification | This data sheet contains final product specifications. | | | |
| Limiting values | | | | |

Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

Application information

Where application information is given, it is advisory and does not form part of the specification.

LIFE SUPPORT APPLICATIONS

These products are not designed for use in life support appliances, devices, or systems where malfunction of these products can reasonably be expected to result in personal injury. Philips customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify Philips for any damages resulting from such improper use or sale.

PURCHASE OF PHILIPS I2C COMPONENTS



Purchase of Philips I²C components conveys a license under the Philips' I²C patent to use the components in the I²C system provided the system conforms to the I²C specification defined by Philips. This specification can be ordered using the code 9398 393 40011.